

PMP6929_REVB BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
4	C1, C2, C3, C4	47uF	Capacitor, Electrolytic, -40 to +105 °C	18x25 mm w/7.5mm lead spacing	EEU-EE2W470S	Panasonic
2	C12, C13	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603		TDK
1	C14	0.033uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
1	C15	30pF	Capacitor, Ceramic, 250V	0603	STD	STD
1	C16	10uF	Ceramic, 35V	1210	Std	STD
4	C17, C18, C19, C20	1000pF	2kV Ceramic Capacitor	1206	1206GC102KAT1A	AVX
1	C21	2200pF	Capacitor, Ceramic, 4700pF, 2kV, X7R, 1812	1812		TDK
1	C22	27uF	Capacitor, Ceramic, vvV, X7R	0.327 X 0.327 inch	PCV1V270MCL1GS	Nichicon
1	C24	15pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C25	3300pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
3	C5, C9, C11	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	STD	STD
2	C6, C7	4.7uF	Capacitor, Ceramic, 50V, X5R, 15%	1210	STD	STD
1	C8	220uF	Capacitor, Aluminum, 35V, ±20%	8x10mm	EEV-FK1V221P	Panasonic
18	D1, D2, D3, D4, D5, D6, D7, D8, D12, D13, D16, D17, D18, D19, D20, D21, D22, D23	MRA4007	Diode, Rectifier, 1A, 1000V, SMA	SMA	MRA4007	ON
2	D10, D11	BAS21LT1G	Diode, Switching, 200-mA, 250V, 385mW	SOT23	BAS21LT1G	On Semi
1	D15	SK4200L	IC DIODE SCHOTTKY 4A 200V SMC	SMC	SK4200L	Micro Commercial Co
2	D26, D27	BAS16	Diode, Switching, SOT23	SOT23		On Semi
1	D9	DNP	Do Not Populate	SOD-123	N/A	N/A
1	L1	1mH	Inductor, SMT, yyA, zzmillionhm	0.398 sq inch	SLF10145T-102MR29-PF	TDK
1	L2	1uH	Inductor, Power Chip, 0.9A, 0.14 Ohms	0805		Coilcraft
3	MOV1, MOV2, MOV4	1210V	MOV,	0.472 x 0.157 inch	V660LA510AP	Littlefuse
1	Q1	STP4N150	N channel 1500V /T0-220	T0-220	STP4N150	ST
8	R1, R2, R3, R4, R5, R6, R7, R32	220K	Resistor, Chip, 1/2W, 0.1%	1210	STD	STD
3	R10, R12, R13	10	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	R11	21.0k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R14	10k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R15	2.55k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R16	1.43	Resistor, Chip, 1/4W, 5%	1210		Std
3	R17, R18, R19	1M	Resistor, 1/4 watt, 5%	1206	STD	STD
1	R20	681k	Resistor, Chip, 1/2W, 0.1%	1210	STD	STD
1	R21	0.5 Ohm 1/2 W	Resistor, 1/2W, 5%	1210	Std	Std
2	R22, R24	0.5 Ohm 1/2W	Resistor, 1/2W, 5%	1210	Std	Std
1	R23	0.5 Ohm 1/2W	Resistor, 1/2W, 5%	1210	Std	Std
1	R25	5.1k	Resistor, Chip, 5.1k, 1%, 0805	0805		Std
1	R27	7.5k	Resistor, Chip, 7.5k, 1%, 0805	0805		Std
1	R28	1.15k	Resistor, Chip, 1.15k, 1%, 0805	0805		Std
1	R29	10k	Resistor, Chip, 10k, 1%, 0805	0805		Std
1	R30	100k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R31	1k	Resistor, Chip, 4.75k, 1%, 0805	0805		Std
1	R8	63.4k	Resistor, Chip, 1/16W, 1%	0603		Std
1	R9	2.8k	Resistor, Chip, 1/16W, 1%	0603	STD	STD
1	T2	1.5 mH	Transformer,	25 X 31.5 mm	TBD	Triad
4	TP1, TP2, TP5, TP6	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
2	TP3, TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP4, TP8	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8		Texas Instruments
1	U2	H11A817A3S	IC, Optocoupler, 5300-V, 50-160% CTR	0.435 x 0.210 inch	H11A817A3S	Fairchild
1	U5	TL431ACD	IC, Adj Shunt Regulator, 100-mA, 36-V	SO8		TI

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers ("Buyers") who are developing systems that incorporate TI semiconductor products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. **TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design.** TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER'S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer's safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.